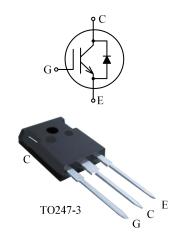


IGBT in advanced TrenchFS Technology with soft and fast recovery anti-parallel diode 具有先进 TrenchFS 技术的 IGBT 且反并联软快恢复二极管

Features:

特性

- 650V TrenchFS technology 650V 沟槽栅场终止技术
- Low conduction and switching losses 低导通和开关损耗
- Positive temperature coefficient 饱和电压正温度系数
- Short Circuit withstand time-5μs 具备5μs短路承受能力



Applications:

应用

● General Inverter 通用变频器

Type	V _{CE} [V]	I _C [A]	V _{CEsat} [V]	T _{jmax} [℃]	Marking	Package
型号	集电极-发射极电压	集电极电流	饱和电压	最高结温	标记	封装
BGN20T65SD	650	20	1.6	175	20T65SD	TO247-3



Maximum Rated Values

最大额定参数

Parameter 参数	Symbol 符号	Value 值	Unit 单位
Collector-emitter voltage, T _j ≥25℃ 集电极-发射极电压,T _j ≥25℃	$ m V_{CE}$	650	V
Collector current,T _C =25℃ 集电极电流,T _C =25℃	I _C	40	
Collector current,T _C =100℃ 集电极电流,Tc=100℃	I_{C}	20	
Pulsed collector current, t_p limited by $T_{j \text{ max}}$ 集电极脉冲电流,脉宽时间受 $T_{j \text{ max}}$ 限制	I _{Cpuls}	80	
Diode forward current, T _C =25℃ 二极管正向电流,Tc=25℃	I_{F}	40	A
Diode forward current, T _C =100℃ 二极管正向电流,T _C =100℃	I_{F}	20	
Diode pulsed current 二极管脉冲电流	I_{Fpuls}	80	
Gate-emitter voltage 栅极-发射极电压	V_{GE}	±20	V
Short Circuit withstand time V _{GE} =15V,V _{CC} ≤400V,T _j ≤150℃ 短路耐受时间	$t_{ m sc}$	5	us
Total power dissipation, T _C =25℃ 总耗散功率,T _C =25℃	P _{tot}	192	W
Operating junction temperature 最高结温	$T_{ m jmax}$	175	
Operating junction temperature 工作结温	$T_{ m jop}$	-40+150	$^{\circ}$
Storage temperature 储存温度	T_{stg}	-55+150	
Soldering temperature,1.6mm from case for 10s 焊接温度	T _{st}	260	
Mounting Torque M3 锁装力矩	Md	0.6	Nm

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Thermal Resistance

热阻

Parameter 参数	Symbol 符号	Value 值	Unit 单位
IGBT Thermal resistance junction to case IGBT 结-管壳热阻	R _{th(j-c)}	0.78	°C/W
Diode Thermal resistance junction to case 二极管结-管壳热阻	R _{th(j-c)}	2.07	°C/W
Thermal resistance junction to ambient 结-环境热阻	R _{th(j-a)}	40	°C/W

Electrical Characteristic at $Tj = 25^{\circ}C$ (unless otherwise specified)

Tj=25℃时电学特性(除非特别声明)

			\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	⁷ alue		
Parameter	Symbol	Conditions		值		T T •4
参数	符号	条件	Min. 最小 值	Typ. 典型 值	Max. 最大 值	Unit 単位

Static Characteristic

静态特性

11 10 14 IT							
Collector-emitter breakdown voltage 集电极-发射极击穿电压	V _{(BR)CES}	V _{GE} =0V, I _C =100uA		650	ı	-	
Collector-emitter saturation voltage 集电极-发射极饱和电压	3 7	cesat $V_{GE}=15V$, $I_{C}=20A$	T _j =25℃	-	1.6	2.0	
	v cesat		T _j =150℃	-	1.8	-	V
Diode forward voltage	VF	$VF \qquad V_{GE}=0V, \\ I_F=20A$	T _j =25℃	-	1.7	2.4	V
二极管正向电压			T _j =150℃	-	1.4	-	
Gate-emitter threshold voltage 栅极-发射极阈值电压	V _{GE(th)}	I _C =300uA, V _{CE} =V _{GE}		5.0	5.8	7.0	
Collector-emitter cut-off current 集电极-发射极截止电流	I _{CES}	V_{CE} =650V, V_{GE} =0V		-	-	100	μΑ
Gate-emitter leakage current 栅极-发射极漏电流	I _{GES}		=0V, ±20V	-200	-	200	nA

Dynamic Characteristic

动态特性

Input capacitance 输入电容	Cies		-	1500	-	
Output capacitance 输出电容	Coes	V _{CE} =25V, V _{GE} =0V, f=1MHz	-	128	-	pF
Reverse transfer capacitance 反向传输电容	Cres		-	28.7	-	

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Gate charge 门极电量	Q _G	V _{CC} =400V,I _C =30A, V _{GE} =15V	-	43.9	-	nC
Short circuit current 短路电流	I _{C(sc)}	V_{CC} =400V, V_{GE} =15V, tpsc \leq 5us, T_{j} =150°C	-	80	-	A

T_j=25℃时开关特性(感性负载)

Parameter	Sambal (Conditions	Value 值			
Parameter 参数	Symbol 符号	条件	Min. 最小 值	Typ. 典型 值	Max. 最大 值	Unit 单位
IGBT Characteristic IGBT 特性						
Turn-on delay time 开通延迟时间	t _{d(on)}		-	40.5	-	
Rise time 上升时间	$t_{\rm r}$	T _j =25℃,	-	48	-	
Turn-off delay time 关断延迟时间	t _{d(off)}	V_{CC} =400V, I_{C} =20A, V_{GE} =-7.5/15V, R_{G} =10 Ω , Energy losses include "tail" and diode	-	70	-	ns
Fall time 下降时间	t_{f}		-	141	-	
Turn-on energy 开通损耗	Eon		-	0.55	-	
Turn-off energy 关断损耗	E _{off}	reverse recovery.	-	0.26	-	mJ
Total switching energy 总开关损耗	E _{ts}		-	0.81	-	
Anti-Parallel Diode Characteristic 反并联二极管特性	:					
Reverse recovery time 反向恢复时间	t _{rr}	Tj=25℃,	-	117	-	ns
Recovered charge 恢复电荷	Qr	V_{R} =400V, I_{F} =20A,	-	345	-	nC
Peak reverse recovery current 反向恢复峰值电流	I_{RM}	diF/dt=390A/μs	-	5.3	-	A

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Switching Characteristic at T_j =150°C (Inductive Load)

Tj=150℃时开关特性(感性负载)

	Symbol 符号	Conditions 条件	Value 值			
Parameter 参数			Min. 最小 值	Typ. 典型 值	Max. 最大 值	Unit 单位
IGBT Characteristic IGBT 特性			1			1
Turn-on delay time 开通延迟时间	t _{d(on)}		-	39.5	-	
Rise time 上升时间	t _r	T _j =150℃,	-	47	-	
Turn-off delay time 关断延迟时间	t _{d(off)}	V_{CC} =400V, I_{C} =20A, V_{GE} =-7.5/15V, R_{G} =10 Ω ,	-	80	-	ns
Fall time 下降时间	t_{f}		-	166	-	
Turn-on energy 开通损耗	Eon	Energy losses include "tail" and diode	-	0.71	-	
Turn-off energy 关断损耗	Eoff	reverse recovery.	-	0.42	-	mJ
Total switching energy 总开关损耗	E_{ts}		-	1.13	-	
Anti-Parallel Diode Characteristic 反并联二极管特性	:					
Reverse recovery time 反向恢复时间	t _{rr}	T _i =150℃,	-	152	-	ns
Recovered charge 恢复电荷	Qr	V_R =400V, I_F =20A,	-	980	-	nC
Peak reverse recovery current 反向恢复峰值电流	I_{RM}	diF/dt=400A/μs	-	8.7	-	A

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ELECTRICAL CHARACTERISTICS 特性曲线

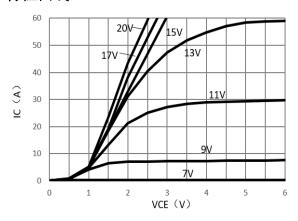


Figure 1. Typical output characteristic($T_j=25^{\circ}C$)

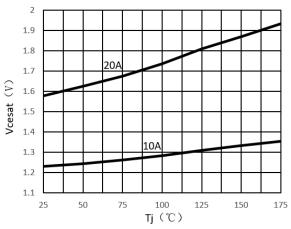


Figure 3. V_{cesat} vs. T_j

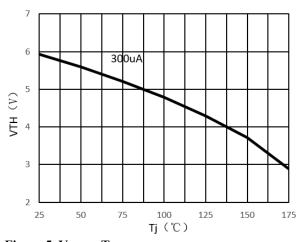


Figure 5. V_{TH} vs. T_j

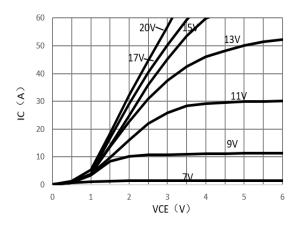


Figure 2. Typical output characteristic(T_j=150℃)

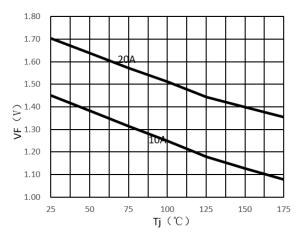


Figure 4. V_F vs. T_j

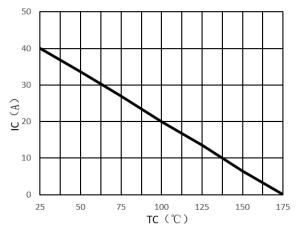


Figure 6. I_C VS T_C

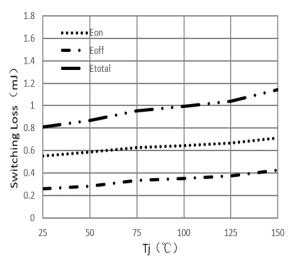


Figure 7. Switching energy losses vs T_j (V_{CE} =400 V_{CE} =15 V_{LC} =20 A_{CE} =10 Ω)

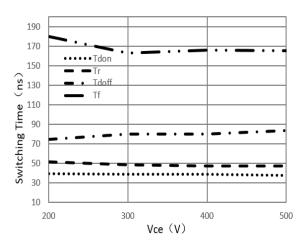


Figure 9. Switching times vs V_{CE} (T_i =150°C, V_{GE} =15V, I_C =20A, R_G =10 Ω)

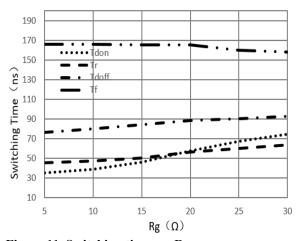


Figure 11. Switching times vs $R_{\rm g}$ $(T_{\rm j}{=}150\,^{\circ}\!C, V_{\rm CE}{=}400V, V_{\rm GE}{=}15V, I_{C}{=}20A)$

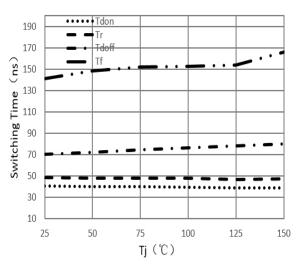


Figure 8. Switching times vs Tj $(T_j{=}25^{\circ}C, V_{GE}{=}15V, I_C{=}20A, R_G{=}10\,\Omega\,)$

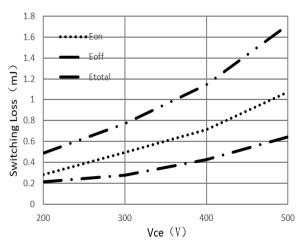


Figure 10. Switching energy losses vs V_{CE} (T_i =150 C, V_{CE} =400V, V_{GE} =15V, I_C =20A)

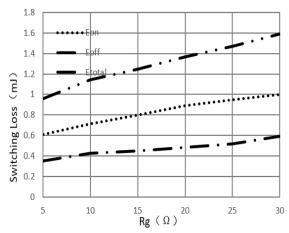
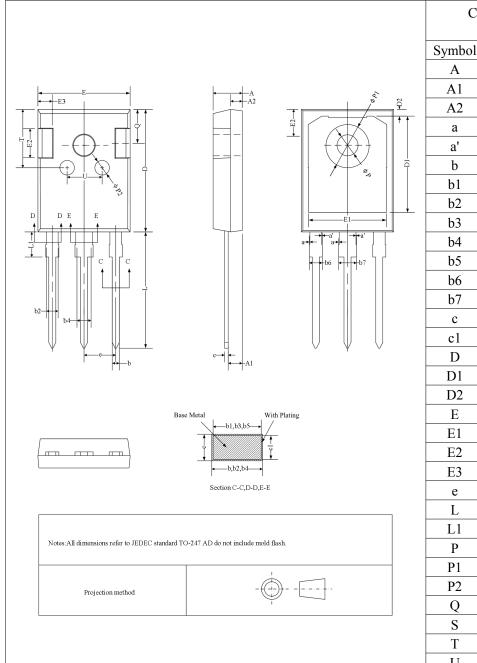


Figure 12. Switching energy losses vs R_g (T_j =150°C, V_{CE} =400V, V_{GE} =15V, I_C =20A)



TO247-3 Outline Dimensions:

TO247-3 外形尺寸



Common Dimensions (Units:Millimeter)							
Symbol	Min.	Nom.	Max.				
A	4.90	5.00	5.10				
A1	2.31	2.41	2.51				
A2	1.90	2.00	2.10				
a	0.00	-	0.15				
a'	0.00	-	0.15				
b	1.16	-	1.26				
b1	1.15	1.20	1.22				
b2	1.96	-	2.06				
b3	1.95	2.00	2.02				
b4	2.96	-	3.06				
b5	2.95	3.00	3.02				
b6	-	-	2.25				
b7	_	-	3.25				
c	0.59	-	0.66				
c1	0.58	0.60	0.62				
D	20.90	21.00	21.10				
D1	16.25	16.55	16.85				
D2	1.05	1.20	1.35				
Е	15.70	15.80	15.90				
E1	13.10	13.30	13.50				
E2	4.90	5.00	5.10				
E3	2.40	2.50	2.60				
e	5.34	5.44	5.54				
L	19.80	19.92	20.10				
L1	-	-	4.30				
P	3.50	3.60	3.70				
P1	-	-	7.40				
P2	2.40	2.50	2.60				
Q	5.60	-	6.00				
S	6.05	6.15	6.25				
Т	9.80	-	10.20				
U	6.00	-	6.40				

Packing

包装

Packing	pcs/tube	tube/ inner box	inner box/ carton	pcs/carton
Tube	30	12	6	2160

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RESTRICTIONS ON PRODUCT USE

- The information contained herein is subject to change without notice.
- BYD Semiconductor Company Limited exerts the greatest possible effort to ensure high quality and reliability. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing products, to comply with the standards of safety in making a safe design for the entire system, including redundancy, fire-prevention measures, and malfunction prevention, to prevent any accidents, fires, or community damage that may ensue. In developing your designs, please ensure that products are used within specified operating ranges as set forth in the most recent products specifications.
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